



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Pro 2110 Small Form Factor Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries (Inside main board)	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Inside power supply. May vary	2
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	power supply fan housing	1
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers	0
Components, parts and materials containing radioactive substances	0

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
LONGITUDE_MAIN_BEZEL	main bezel	111.91	>ABS<	
LONGITUDE_COVER_BEZEL L	main bezel cover	38.70	>ABS<	
LONGITUDE_TRIM_BEZEL	main bezel trim	26.79	>ABS<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 cross screw driver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Refer to disassembly graphic below
- 2.
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Take out the left side panel.

- a. Release Thumb screw x 1.
- b. Remove left side panel and take out it.
- c. Torque: 3 kgf. cm

a.

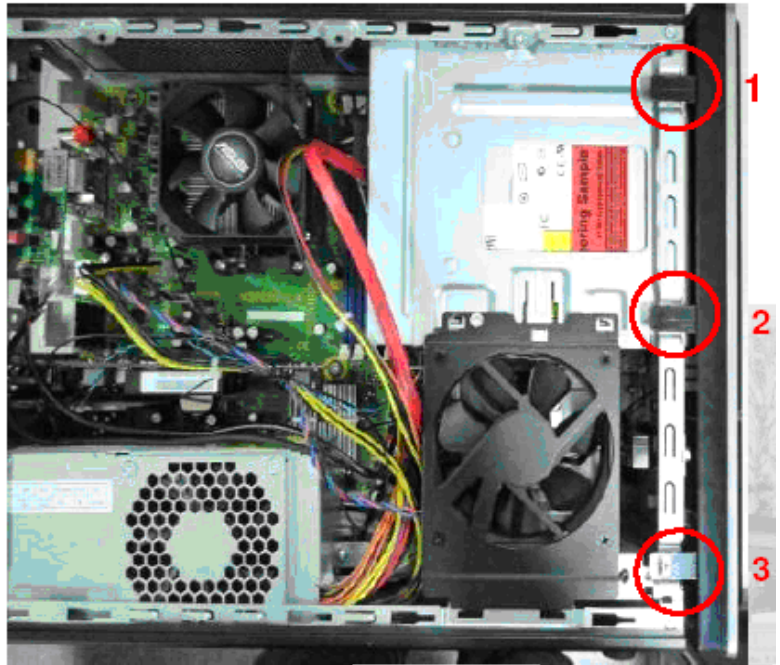


b.



2. Take out the main bezel.

- a. Release main bezel hook 1,2,3.
- b. Take out main bezel.



3. Take out the Cable tie

a. Release cable tie.

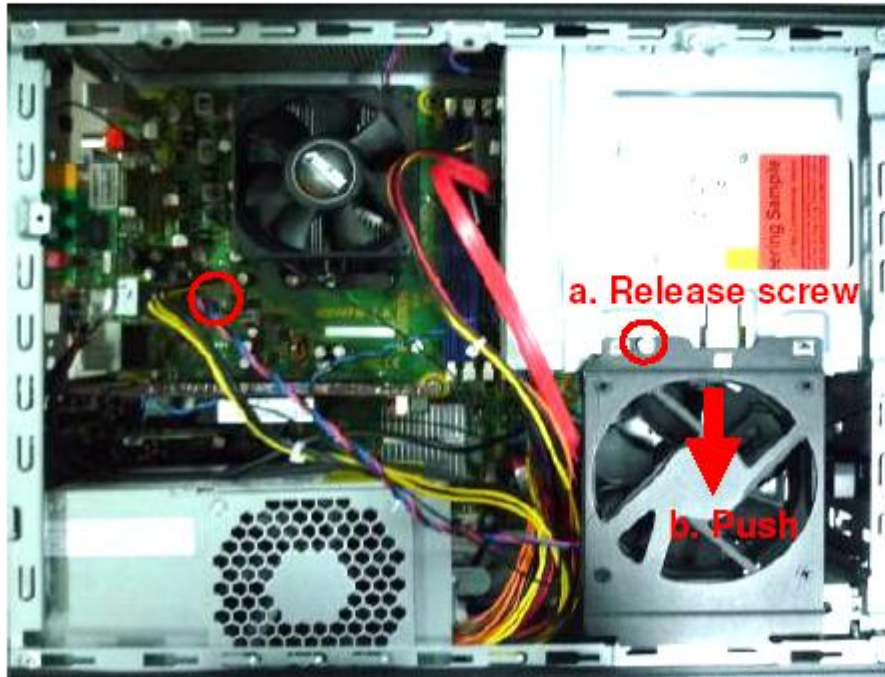
a.



4. Disassembly System fan

- a. Release system fan bracket screw x1
- b. Push system fan along the arrow and remove the system fan cable
- c. Torque : 5 kgf. Cm

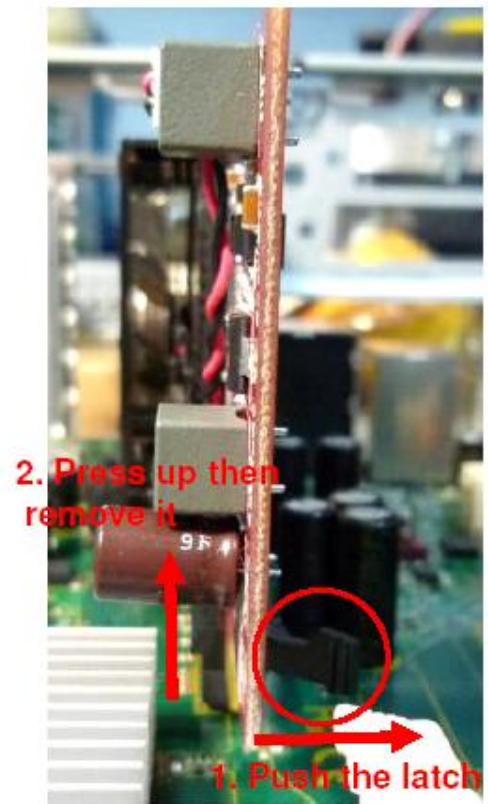
a & b.



5. Disassembly VGA and PCI cards

a. Remove VGA card.

a



b. Remove WLAN and WLAN card.

b .



c. Remove Wireless antenna cable (1 & 2) .

c.



6. Disassembly Power Supply

a. Remove 24 Pin power cable.

a.

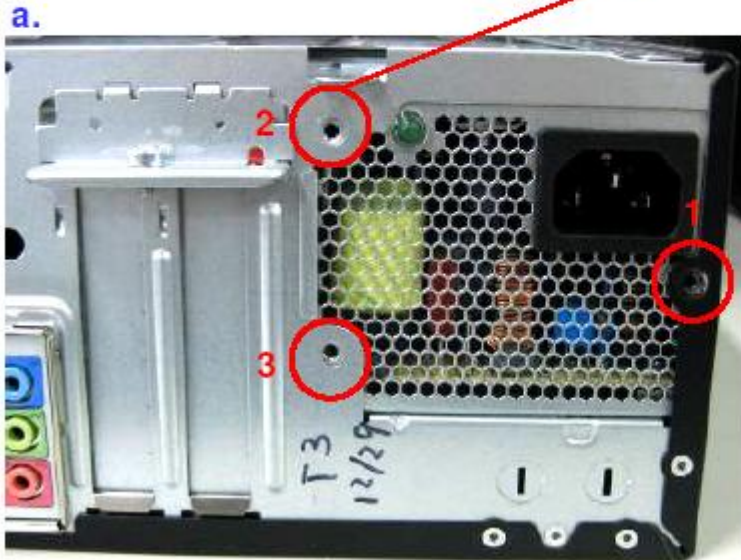


- b. Release screw x3.
- c. Torque: 5 kgf. cm

Use screw x 3



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- d. Press power supply latch.
- e. Put power supply along the arrow.

d & e.

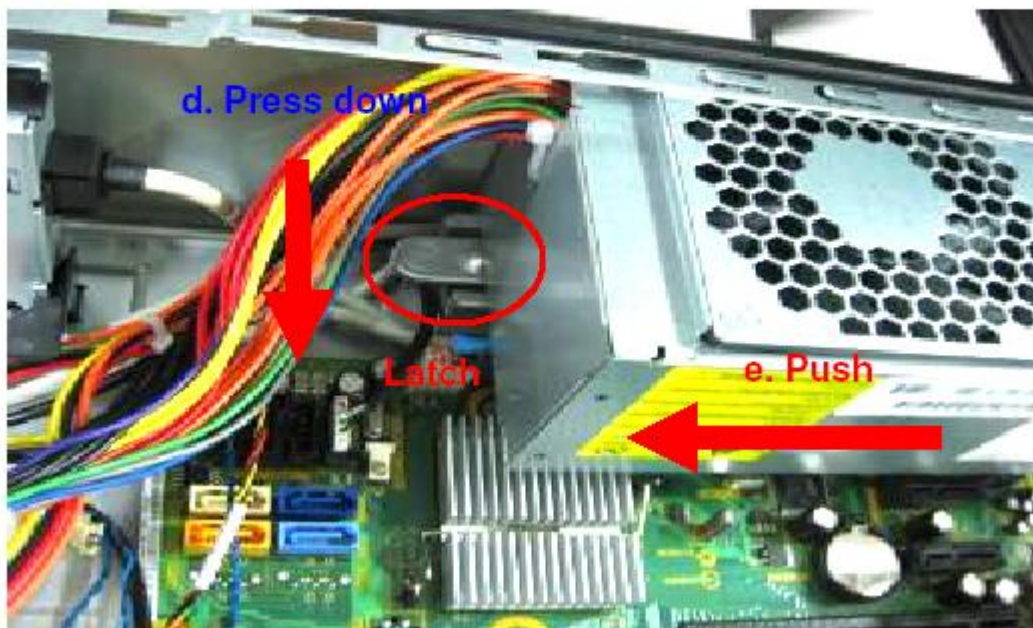


FIGURE 1. Screwed off the screws

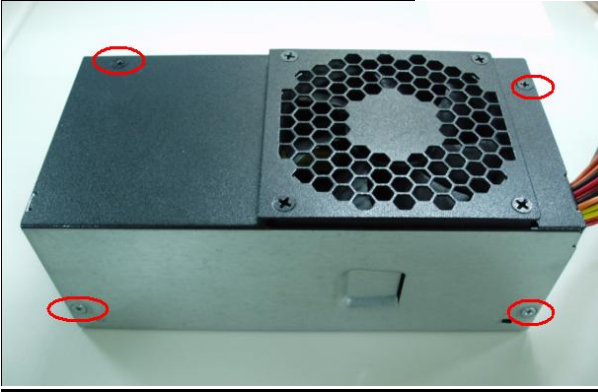


FIGURE 2. Pull out the metal cover

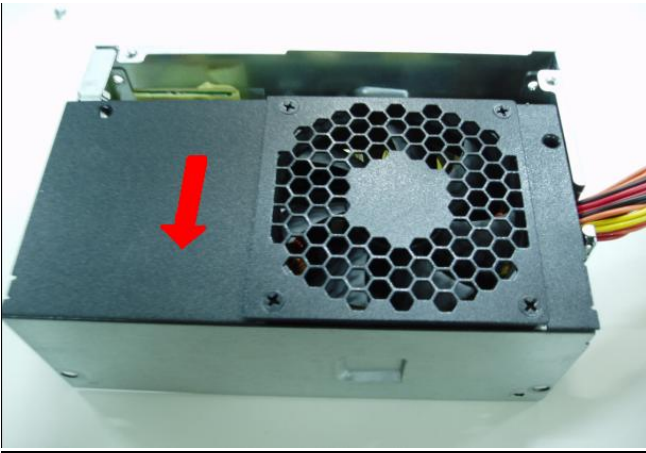


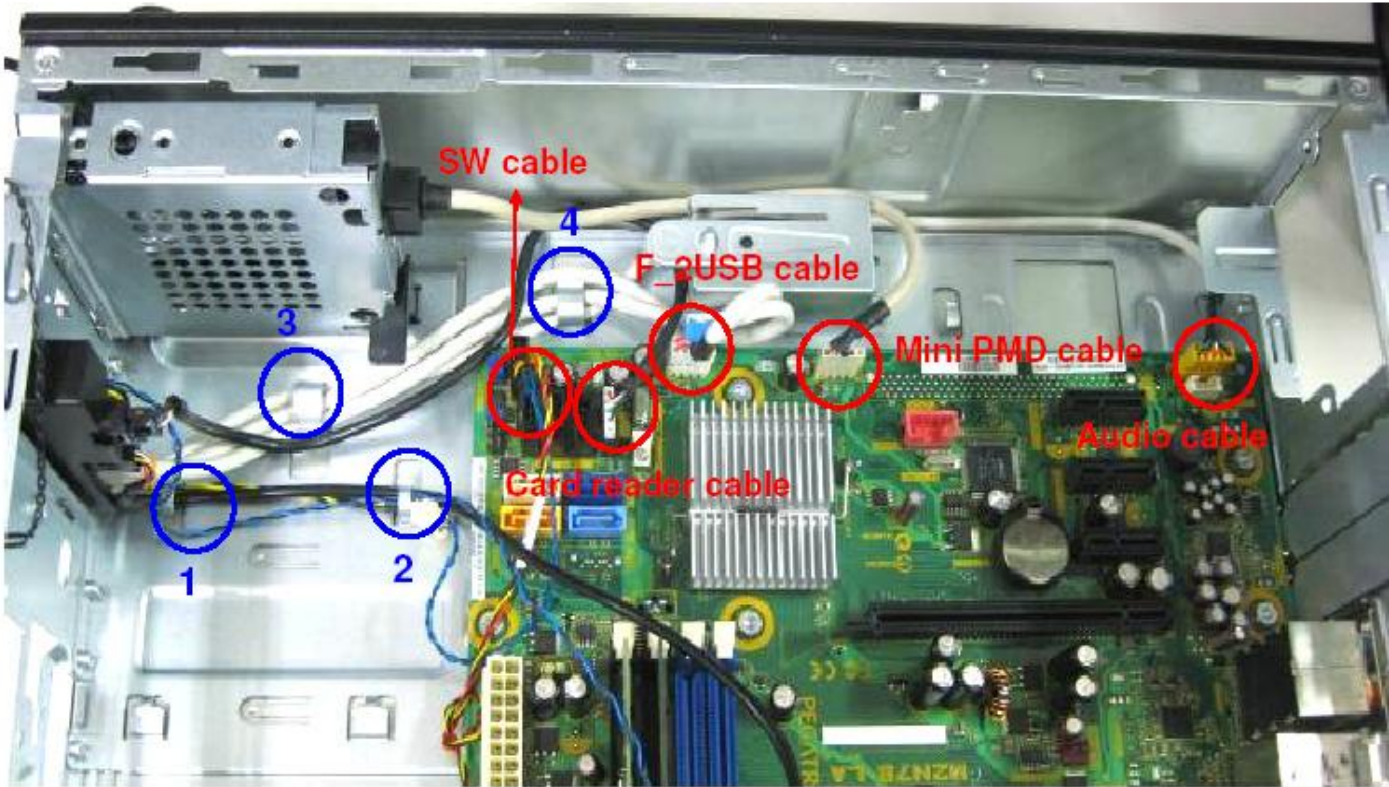
FIGURE 4. Screwed off the screws & remove PCBA



FIGURE 5. Remove the electrolytic capacitors



7. Disassembly Card reader module cable



** Please remove these cable from Hook(1,2,3,4)

8. Disassembly Card reader module

- a. Release screw x1
- b. Push the card reader module along the arrow.
- c. Torque: 5 kgf. cm

screw x 1

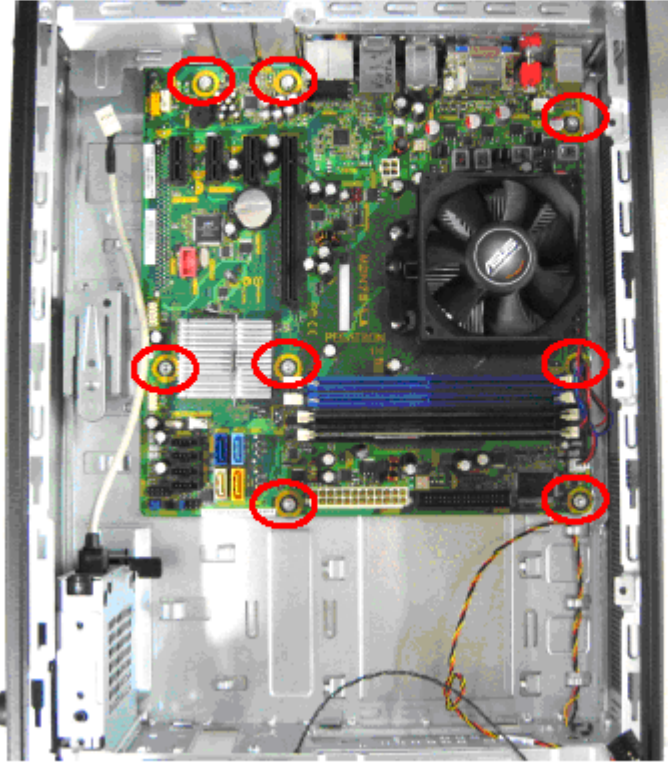


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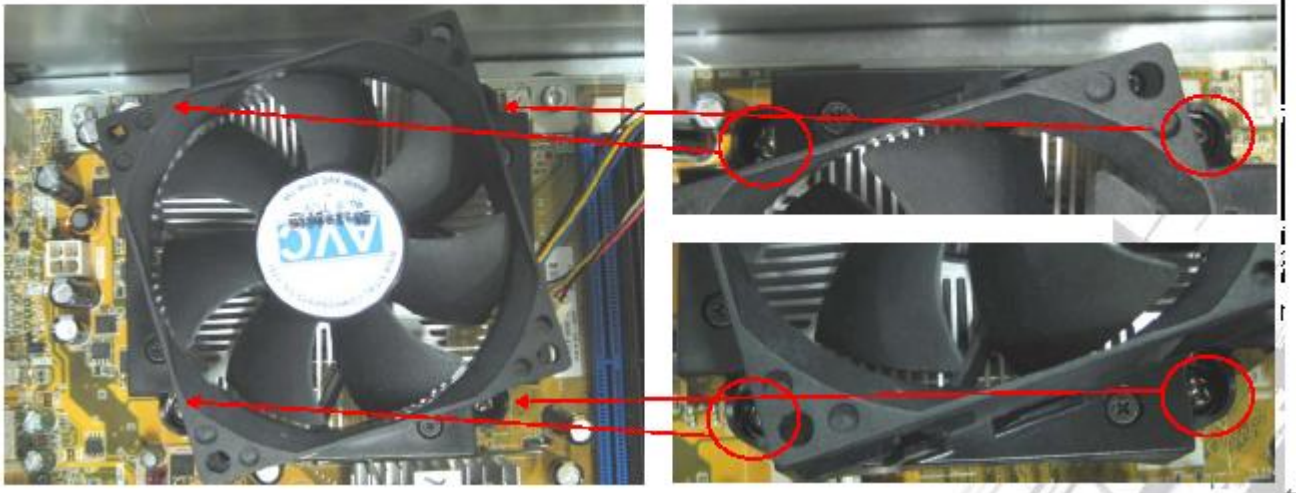
9 . Disassembly MB

a. Release screw and take out the MB from chassis.



b. remove Heat sink from MB

- 1.Unfix 4 screw front Heat Sink
- 2.Remove Heat Sink



c. remove coin cell from MB

